

Features

- On-state rms current, $I_{T(RMS)}$ 1 A
- Repetitive peak off-state voltage, $V_{DRM/VRRM}$ 600 or 800 V
- Triggering gate current, $I_{GT(Q1)}$ 3 to 25 mA

Applications

- AC switching
- Home appliances

Description

The Z01 series is suitable for general purpose AC switching applications. These devices are typically used in applications such as home appliances (electrovalve, pump, door lock, small lamp control), fan speed controllers,...

Different gate current sensitivities are available, allowing optimized performance when driven directly through microcontroller.

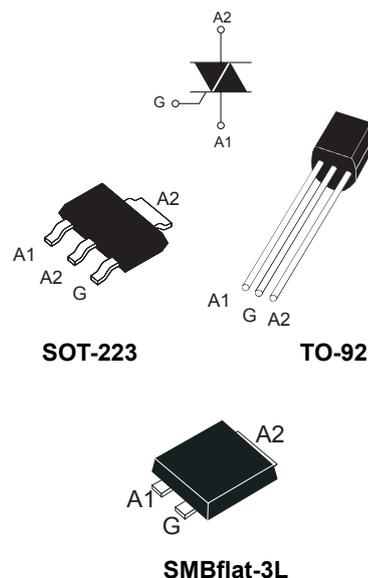
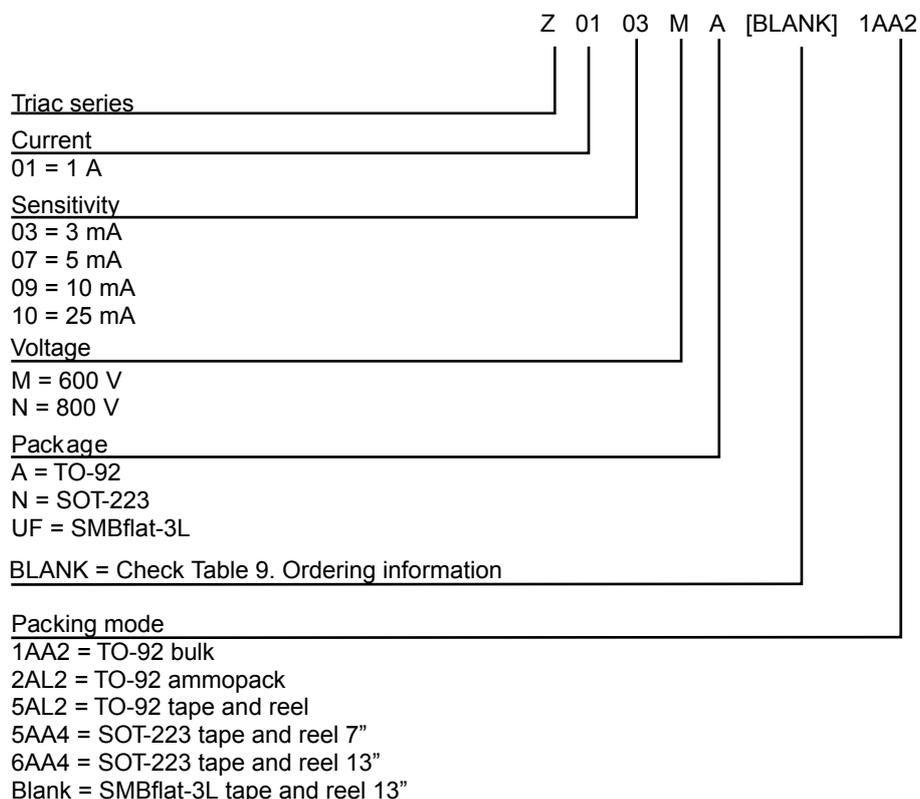


Figure1. Ordering information scheme



1 Characteristics

Table 1. Absolute maximum ratings

| Symbol | Parameters | Value | Unit | |
|--------------|---|--|-------------|-------------|
| $I_{T(RMS)}$ | RMS on-state current (full sine wave) | SOT-223 $T_{tab} = 90\text{ °C}$ | 1 | A |
| | | TO-92 $T_L = 50\text{ °C}$ | | |
| | | SMBflat-3L $T_{tab} = 107\text{ °C}$ | | |
| I_{TSM} | Non repetitive surge peak on-state current (full cycle, T_j initial = 25 °C) | F = 50 Hz $t_p = 20\text{ ms}$ | 8 | A |
| | | F = 60 Hz $t_p = 16.7\text{ ms}$ | 8.5 | |
| I^2t | I^2t value for fusing | $t_p = 10\text{ ms}$ | 0.35 | A^2s |
| di/dt | Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$, $t_r \leq 100\text{ ns}$ | F = 120 Hz $T_j = 125\text{ °C}$ | 20 | $A/\mu s$ |
| I_{GM} | Peak gate current | $t_p = 20\text{ }\mu s$ $T_j = 125\text{ °C}$ | 1 | A |
| $P_{G(AV)}$ | Average gate power dissipation | $T_j = 125\text{ °C}$ | 1 | W |
| T_{stg} | Storage junction temperature range | | -40 to +150 | $^{\circ}C$ |
| T_j | Operating junction temperature range | | -40 to +125 | $^{\circ}C$ |

Table 2. Electrical characteristics ($T_j = 25\text{ °C}$, unless otherwise specified)

| Symbol | Parameters | Quadrant | | Value | | | | Unit |
|-------------------|--|--------------|------|-------|----|----|-----|-----------|
| | | | | Z01 | | | | |
| | | | | 03 | 07 | 09 | 10 | |
| $I_{GT}^{(1)}$ | $V_D = 12\text{ V}$, $R_L = 30\text{ }\Omega$ | I - II - III | Max. | 3 | 5 | 10 | 25 | mA |
| | | IV | | 5 | 7 | 10 | 25 | |
| V_{GT} | | All | Max. | 1.3 | | | | V |
| V_{GD} | $V_D = V_{DRM}$, $R_L = 3.3\text{ k}\Omega$, $T_j = 125\text{ °C}$ | All | Min. | 0.2 | | | | V |
| $I_H^{(2)}$ | $I_T = 50\text{ mA}$ | | Max. | 7 | 10 | 10 | 25 | mA |
| I_L | $I_G = 1.2 I_{GT}$ | I - III - IV | Max. | 7 | 10 | 15 | 25 | mA |
| | | II | Max. | 15 | 20 | 25 | 50 | |
| $dV/dt^{(2)}$ | $V_D = 67\% V_{DRM}$ gate open, $T_j = 110\text{ °C}$ | | Min. | 10 | 20 | 50 | 100 | $V/\mu s$ |
| $(dV/dt)_c^{(2)}$ | $(di/dt)_c = 0.44\text{ A/ms}$, $T_j = 110\text{ °C}$ | | Min. | 0.5 | 1 | 2 | 5 | $V/\mu s$ |

1. Minimum I_{GT} is guaranteed at 5% of I_{GT} max.

2. For both polarities of A2 referenced to A1

Table 3. Static electrical characteristics

| Symbol | Test conditions | T_j | | Value | Unit |
|------------------------|--|--------|------|-------|------|
| $V_T^{(1)}$ | $I_{TM} = 1.4 \text{ A}$, $t_p = 380 \mu\text{s}$ | 25 °C | Max. | 1.60 | V |
| $V_{TO}^{(1)}$ | Threshold on-state voltage | 125 °C | Max. | 0.95 | V |
| R_d | Dynamic resistance | 125 °C | Max. | 400 | mΩ |
| I_{DRM} I_{RRM} | $V_{DRM} = V_{RRM}$ | 25 °C | Max. | 5 | μA |
| | | 125 °C | | 0.5 | mA |

1. For both polarities of A2 referenced to A1

Table 4. Thermal resistance

| Symbol | Parameters | | Max. value | Unit |
|---------------|--|------------|------------|------|
| $R_{th(j-t)}$ | Max. junction to tab (AC) | SOT-223 | 25 | °C/W |
| | | SMBflat-3L | 14 | |
| $R_{th(j-l)}$ | Max. junction to lead (AC) | TO-92 | 60 | |
| $R_{th(j-a)}$ | Junction to ambient ($S^{(1)} = 5 \text{ cm}^2$) | SOT-223 | 60 | |
| | | SMBflat-3L | 75 | |
| | Junction to ambient | TO-92 | 150 | |

1. Copper surface under tab.

1.1 Characteristics (curves)

Figure 1. Maximum power dissipation versus on-state RMS current (full cycle)

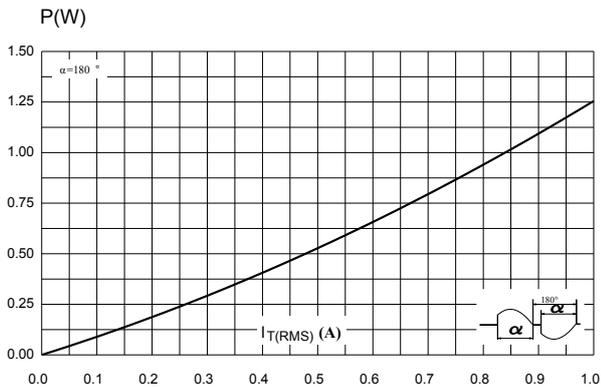


Figure 2. RMS on-state current versus lead (TO-92) or tab (SOT-223, SMBflat-3L) temperature (full cycle)

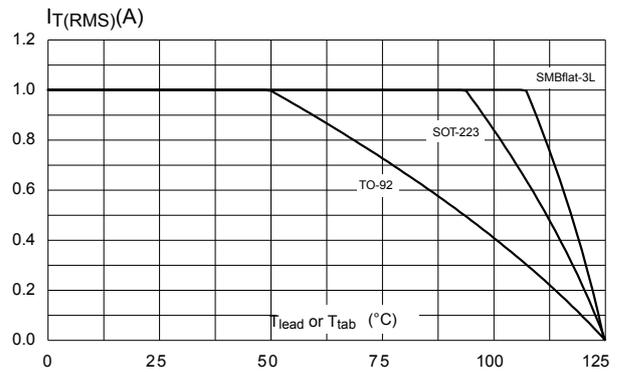


Figure 3. On-state rms current versus ambient temperature (free air convection full cycle)

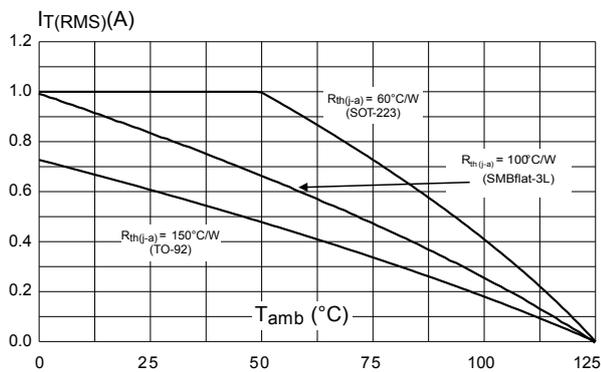


Figure 4. Relative variation of thermal impedance versus pulse duration ($Z_{th(j-a)}$)

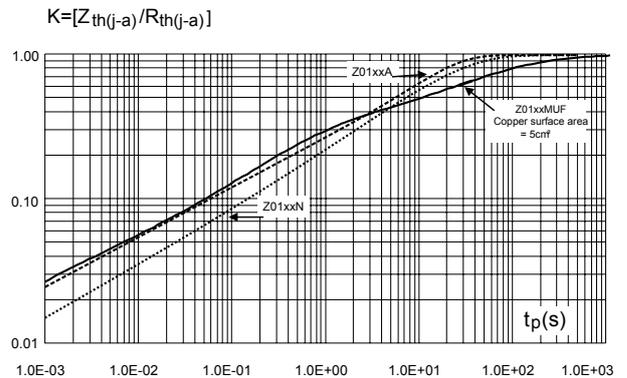


Figure 5. Relative variation of holding current and latching current versus junction temperature (typ. values)

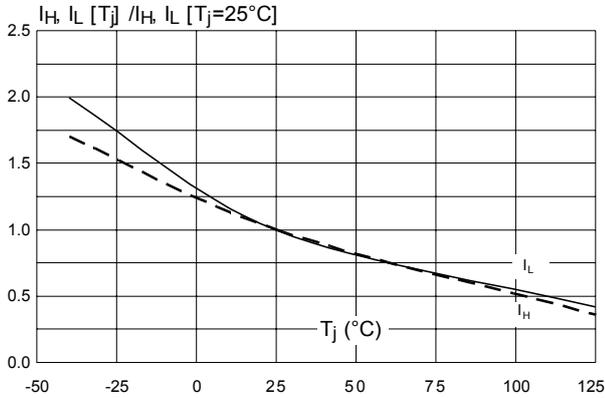


Figure 6. Relative variation of gate trigger current (I_{GT}) and voltage (V_{GT}) versus junction temperature

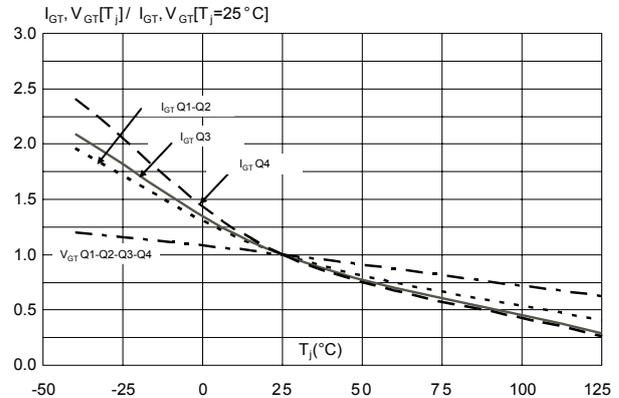


Figure 7. Surge peak on-state current versus number of cycles

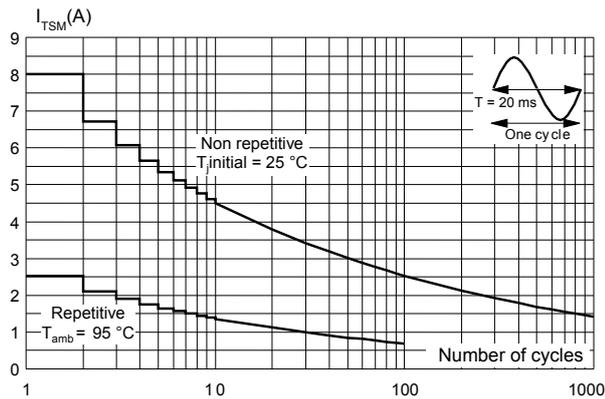


Figure 8. Non-repetitive surge peak on-state current and corresponding value of I^2t sinusoidal pulse width

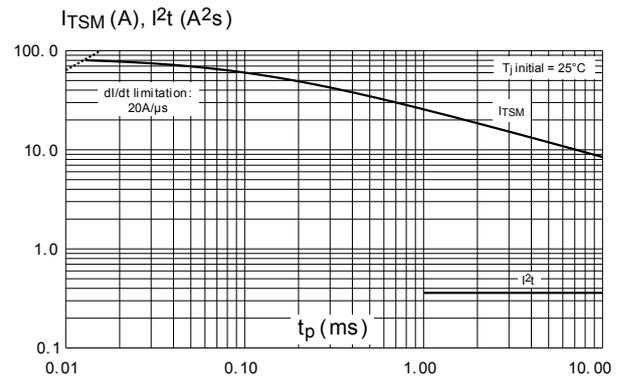


Figure 9. On-state characteristics (maximum values) ($I_{TM} = f(V_{TM})$)

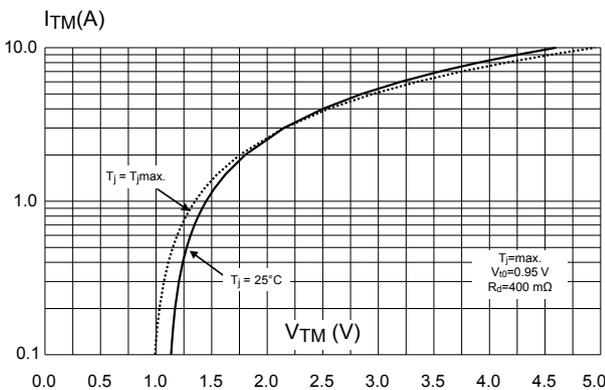


Figure 10. Relative variation of critical rate of decrease of main current (dI/dt) versus junction temperature

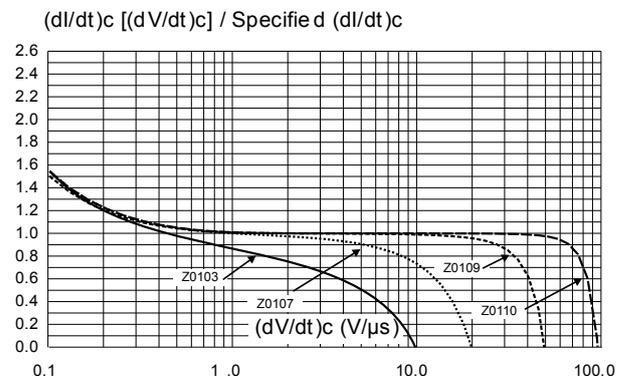


Figure 11. Relative variation of critical rate of decrease of main current (dI/dt) versus junction temperature

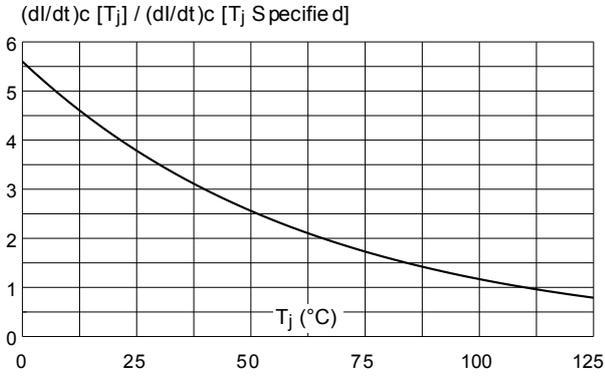


Figure 12. SOT-223 and SMBflat-3L thermal resistance junction to ambient versus copper surface under case

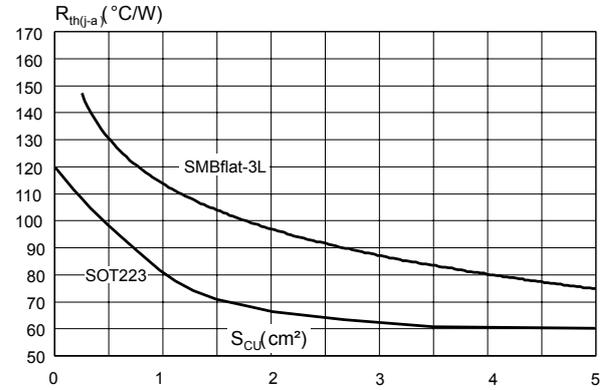


Figure 13. Relative variation of static dV/dt immunity versus junction temperature (gate open)

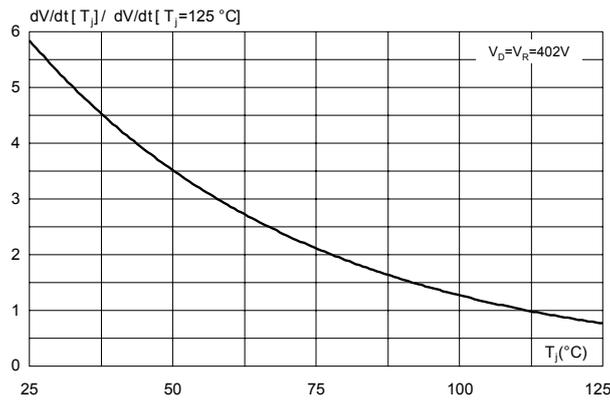


Figure15. SOT-223 package outline

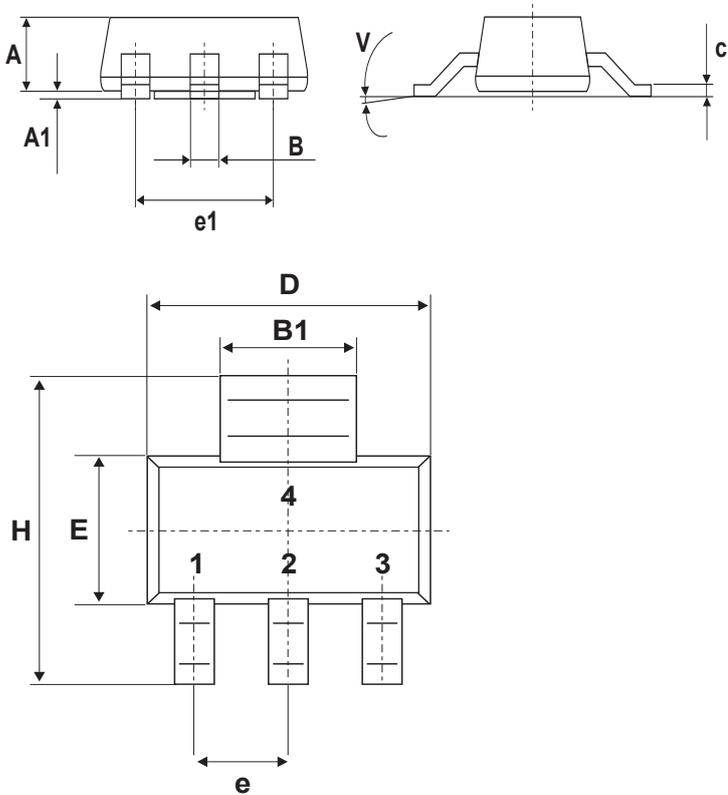


Table 5. SOT-223 package mechanical data

| Ref. | Dimensions | | | | | |
|------|-------------|------|------|-----------------------|--------|--------|
| | Millimeters | | | Inches ⁽¹⁾ | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | | | 1.80 | | | 0.0709 |
| A1 | | 0.02 | 0.10 | | 0.0008 | 0.0039 |
| B | 0.60 | 0.70 | 0.85 | 0.024 | 0.0276 | 0.0335 |
| B1 | 2.90 | 3.00 | 3.15 | 0.114 | 0.1181 | 0.1240 |
| c | 0.24 | 0.26 | 0.35 | 0.009 | 0.0102 | 0.0138 |
| D | 6.30 | 6.50 | 6.70 | 0.248 | 0.2559 | 0.2638 |
| e | | 2.3 | | | 0.0906 | |
| e1 | | 4.6 | | | 0.1811 | |
| E | 3.30 | 3.50 | 3.70 | 0.130 | 0.1378 | 0.1457 |
| H | 6.70 | 7.00 | 7.30 | 0.264 | 0.2756 | 0.2874 |
| V | 10° max. | | | | | |

1. Inches only for reference

Figure16. SOT-223 footprint (dimensions in mm)

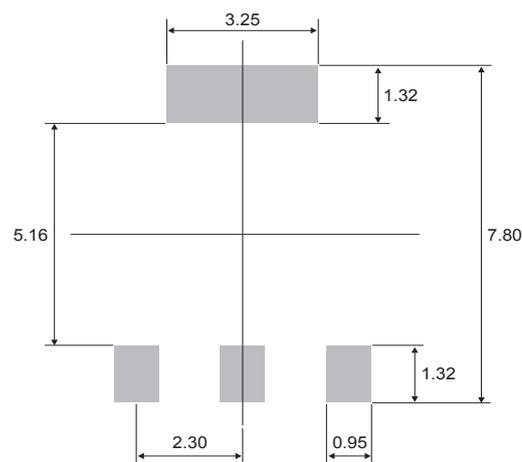


Figure17. TO-92 package outline

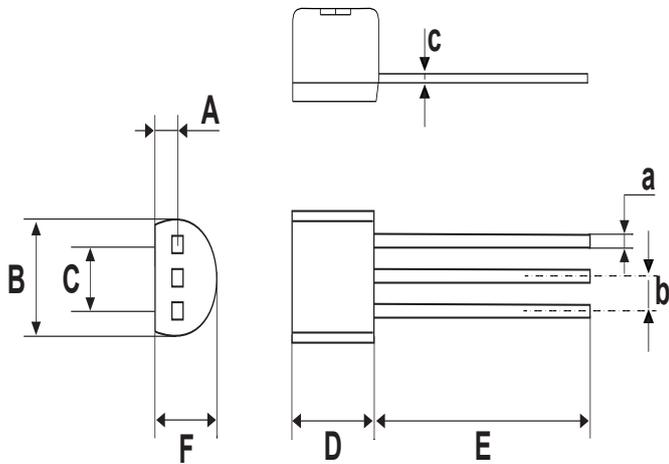


Table 6. TO-92 package mechanical data

| Ref. | Dimensions | | | | | |
|------|-------------|------|------|-----------------------|--------|--------|
| | Millimeters | | | Inches ⁽¹⁾ | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | | 1.35 | | | 0.0531 | |
| B | | | 4.70 | | | 0.1850 |
| C | | 2.54 | | | 0.1000 | |
| D | 4.40 | | | 0.1732 | | |
| E | 12.70 | | | 0.5000 | | |
| F | | | 3.70 | | | 0.1457 |
| a | | | 0.50 | | | 0.0197 |
| b | | 1.27 | | | 0.500 | |
| c | | | 0.48 | | | 0.0189 |

1. Inches dimensions given for information

Figure18. SMBflat-3L package outline

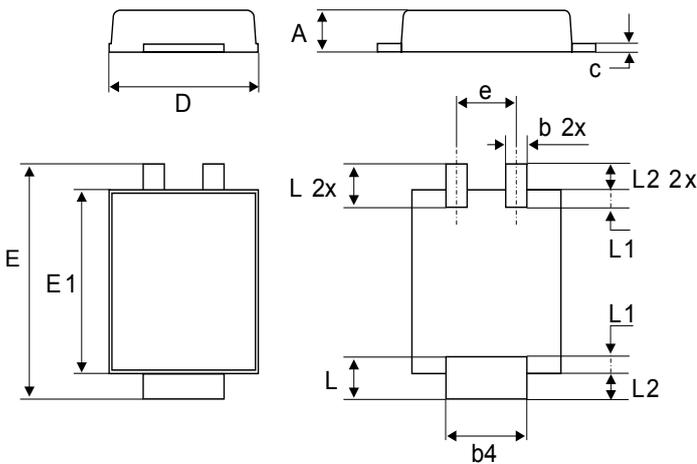


Table 7. SMBflat-3L mechanical data

| Ref. | Dimensions | | | | | |
|------|-------------|------|------|--------|-------|-------|
| | Millimeters | | | Inches | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 0.90 | | 1.10 | 0.035 | | 0.044 |
| b | 0.35 | | 0.65 | 0.014 | | 0.026 |
| b4 | 1.95 | | 2.20 | 0.070 | | 0.087 |
| c | 0.15 | | 0.40 | 0.005 | | 0.016 |
| D | 3.30 | | 3.95 | 0.129 | | 0.156 |
| E | 5.10 | | 5.60 | 0.200 | | 0.221 |
| E1 | 4.05 | | 4.60 | 0.159 | | 0.182 |
| L | 0.75 | | 1.50 | 0.029 | | 0.060 |
| L1 | | 0.40 | | | 0.016 | |
| L2 | | 0.60 | | | 0.024 | |
| e | | 1.60 | | | 0.063 | |

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